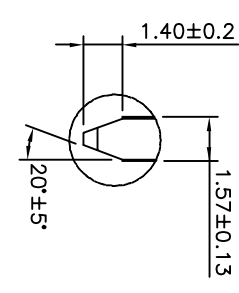
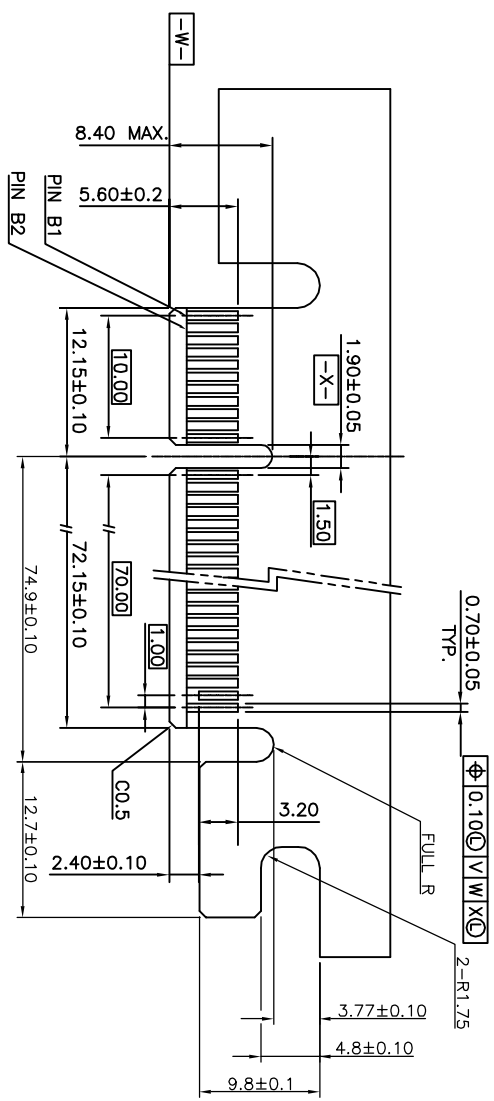


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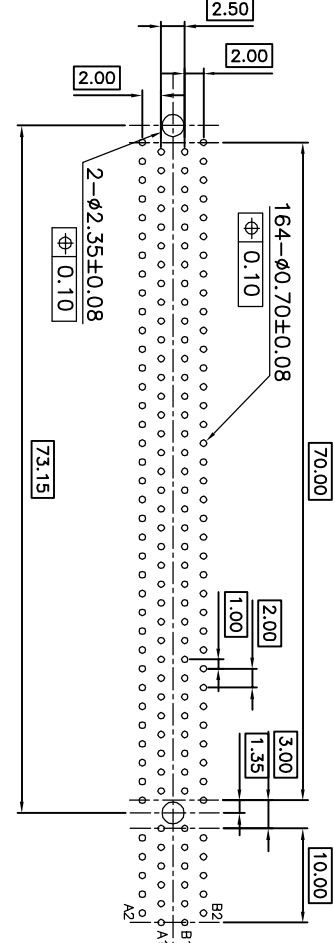
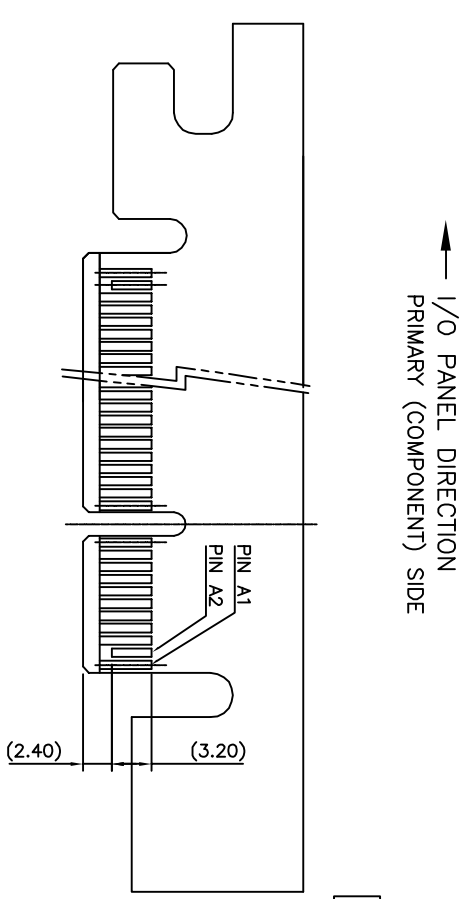
22526

mat'l code		ttr		ecn no		dr		dtdt		linear		tolerances unless otherwise specified		CUSTOMER COPY		title	
A	T05-0046	J.H	2/23/05							.XX ± 0.25		.X ± 0.38	projection	MM	product family	EDGE CARD	code
B	T05-0067	J.H	3/28/05							.XXX ± 0.10		0° ± 2°	size	dwg no	10046742	TWN	code
C	T05-0227	J.H	09/30/05										chr	STERLING LN	2/23/05	1 of	
D	T06-0187	J.H	11/13/06										chr	HC LIOU	2/23/05	1 of	
E	T07-1125	J.H	08/02/07										chr	STERLING LN	2/23/05	1 of	



SCALE 2:1

ADD-IN CARD EDGE-FINGER DIMENSIONS



RECOMMENDED FOOTPRINT LAYOUT

I/O PANEL DIRECTION
SECONDARY (SOLDER) SIDE

I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE

mod'l. code	tolerances unless otherwise specified		CUSTOMER COPY	FCI	www.fciconnect.com
itr	ecn no	dr	date	linear	.XX ± 0.25
E				angles	° ± 2°
				dr	JASON HSU 2/23/05
				engr	JASON HSU 2/23/05
				chr	STERLING LIN 2/23/05
				qppd	HC LIU 2/23/05
sheet	revision			scale	1:1
index	sheet			product family	EDGE CARD
				size dwg no	10046742
				code	TWN
				sheet	2 of

1 | 2

ACAD

3

code code
22526

4



1 | 2

3

4

NOTES: 1. MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0, COLOR IN BLACK.
 LATCHES: THERMOPLASTIC WITH GLASS FIBER, UL94 HB, COLOR IN BLACK.
 CONTACTS: COPPER ALLOY.
 BOARDLOCKS: COPPER ALLOY.

2. FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
 100u"MIN. TIN/LEAD OR 60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,
 50u"MIN. NICKEL UNDERPLATING OVER ALL.
 BOARDLOCKS : 100u" TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,
 50u"MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 20 DEGREE.

4. DURABILITY: 50 CYCLES.

5. ROHS COMPATIBLE PRODUCT SPECIFICATIONS

a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE.
 b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C±5C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10046742 -X X X X X X X X LF

HOUSING COLOR OPTIONS

- 1-BLACK FOR BASE & RM
- 2-BLACK FOR BASE & WHITE FOR RM
- 3-BLUE (287U) FOR BASE & RM
- 4-BLUE (297U) FOR BASE & RM

PEGS OPTIONS

- 1-METAL & PLASTIC COMPOUND

TERMINAL PLATING OPTIONS

- 0-50u" Ni: UNDERPLATE
- 30u" Au CONTACT AREA
- 100u" TIN TAIL AREA
- 1-50u" Ni: UNDERPLATE
- 15u" Au CONTACT AREA
- 100u" TIN TAIL AREA
- 2-50u" Ni: UNDERPLATE
- GOLD FLASH CONTACT AREA
- 100u" TIN TAIL AREA
- 3-50u" Ni: UNDERPLATE
- 30u" Au CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 4-50u" Ni: UNDERPLATE
- 15u" Au CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 5-50u" Ni: UNDERPLATE
- GOLD FLASH CONTACT AREA
- 100u" TIN/LEAD TAIL AREA

APPLICATIONS

BLANK - LEAD CONTAIN FOR PLATING OPTIONS 3,4,5
 LF - LEAD FREE FOR PLATING OPTIONS 0,1,2

PACKAGING OPTIONS

- T-TRAY PACKAGING

POS OPTIONS

- 3-164

TAIL LENGTH OPTION (DIM A)

- 1- 3.10MM
- 2- 2.30MM

mat'l. code	ecn no	dr	date	linear	angular	tolerances unless otherwise specified	projection	title	product family	code
E				.XX ± 0.25	0° ± 2°		MM	PCI-E INTEGRATED TYPE CARD EDGE ASSY	EDGE CARD	TWIN
				XXX ± 0.10						3 of
				engr JASON HSU 2/23/05	chr STERLING LIN 2/23/05		scale 1:1		10046742	
				pppl HC LIOU 2/23/05						
sheet	revision									
index	sheet									

1 | 2

3

4

ACAD

code code
22526